



QP TECHNOLOGIES

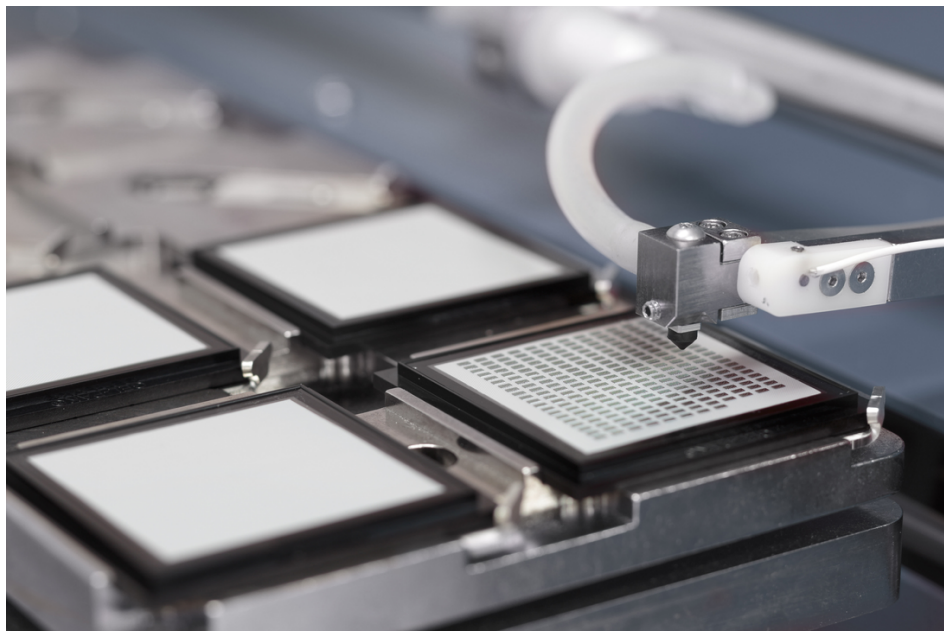
Summer 2022

Technology Focus: Services

Services Beyond Packaging to help you get new products to market

QP Technologies is known for offering a wide range of package types. We also provide a variety of semiconductor manufacturing services to meet your packaging and assembly requirements. These include wafer preparation (backgrinding, dicing, die sort and inspection), IC assembly processes for a variety of package types and materials, laser micromachining, and design and engineering services.

Our wafer-preparation services are available as part of your complete packaging and assembly project, or as standalone services based on your specific needs. Leveraging our advanced wafer processing equipment, QP Technologies offers expert backgrinding of many types and sizes of wafers to meet all of your packaging needs. We also offer wafer dicing and pick-and-place services. Key applications for our wafer prep capabilities include sensors, LEDs and MEMS devices.



For your assembly requirements, we offer a full range of services. Our prototype IC assembly services include wafer preparation (as noted above), die bonding, IC packaging, wire bonding, encapsulation, flattening/remolding, marking/branding IC packages and BGA sphere attach. To address your advanced assembly needs, we work with chip-on-board (COB) / chip-on-flex (COF), multichip modules (MCMs), systems-in-package (SiPs), flip-chip bonding, stacked die, chiplets, and other structures.

If you have requirements for laser micromachining, we can meet them in a variety of ways. Using a precision ND:YAG laser system, we can cut, shape and mark virtually any material, including laminates, composites, plastic, glass, ceramic, silicon and metal.

We also have a full range of design and engineering services available for fabless chipmakers. We collaborate with you to help you conceptualize new products, design and fabricate custom packages, and then complete the assembly process with your die, producing a complete turnkey solution for substrate-based assemblies.

Employee Spotlights

Customers may not always stop to think about the internal processes QP Technologies employs in managing our manufacturing line and the various projects that we have in the works. In this special summer edition of the newsletter, we profile two of our team members who work each day to ensure that production runs smoothly.

Jose Doronilla, Manufacturing Planner

The Covid pandemic has posed numerous challenges, including the well-documented supply chain issues that continue to linger. Like most the rest of the industry, QP Technologies has been affected, but the combination of stable suppliers and skilled manufacturing planner Jose Doronilla has helped to minimize the impact of these challenges on the business.

A supply chain professional with 15+ years' experience in the semiconductor industry, Jose spent more than a decade with Cohu's Broadcast Microwave System and Delta Design subsidiaries, where he held a succession of positions



including planning and scheduling supervisor, master scheduling, program lead, and supply chain operations manager. During his last years at Delta Design, Jose helped to successfully transfer Tri-Temp test handler systems to a high-volume manufacturing site in Malaysia while supporting customer build ramps, sourcing and localizing critical modules.

Jose joined QP Technologies in January of this year to support the company's Materials Organization Team in developing efficient production planning and scheduling for QP's fast-paced, high-mix production environment. He drives day-to-day resource planning, coordinating with multiple departments, and is leading the company's migration to a new business system that will help to further streamline production planning and management.

"QP is growing quickly, and we're starting to bring in some really exciting customers, with big names and really cool new projects," said Jose. "Having new systems and processes in place will allow us to take on these projects and execute them even more efficiently, helping us manage and direct our growth."

In his spare time, Jose enjoys taking advantage of San Diego's beautiful weather to pursue cycling and running.



Carmen Maraya, Production Manager

At the other end of the spectrum in terms of tenure with QP Technologies, Carmen Maraya will have been with the company for 22 years in August. She has seen it through several incarnations – first, as a small division of SAIC, then as part of Delphon (both under its former moniker Quik-Pak), and then, when it became a division of Promex Industries in 2015 and was rebranded as QP Technologies in 2021. As production manager, Carmen oversees the entire production floor, setting the project schedules and allocating resources. She has two supervisors reporting to her, on the morning and evening shifts, and she works closely with them, as well

as with Jose, his manager, materials director Mel Cruz, and QA manager Annette Aquino. Carmen is on the production floor every day to ensure things run smoothly, noting that the increased mix of quick-turn and longer-lead projects has heightened the challenges associated with her job – as have the protracted industry supply-chain issues.

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Carmen isn't daunted by these or other challenges that have arisen over the years. She enjoys helping the company to grow and expand its production capabilities, and she also relishes mentoring her supervisors and operators, helping them to learn best practices so that they can advance their careers. She's in the process of hiring and training to build a full staff for the second shift, and is excited about the opportunities this will enable. "We're growing really fast, so we have an expansion planned, and we're going to buy more equipment, which will give us more ability to meet our customers' schedule demands," Carmen noted, adding that when the company moved into the new building in Escondido, it was built out with just such future needs in mind.

While she loves her job, Carmen values her free time, as well. When she's not at work, she spends as much time as possible with her five grandchildren. She also enjoys ballroom dancing with her husband, and they have performed at parties and other occasions. Nimble on the dance floor and the production floor – what a combination!

News Highlight: Summer Brings Tradeshow Success

The summer of 2022 has been a busy one for QP Technologies, as we participated in several key shows for our technology and target markets. In every case, it was clear that people were very happy to be attending in person again after two years of being restricted to remote/virtual participation.

The IEEE Electronic Components Technology Conference (ECTC), held in early June in San Diego, was well attended, with foot traffic seemingly back to pre-Covid levels. We were able to meet with existing customers as well as garner significant new leads. The industry is going strong, and it was great being able to chat with vendors and customers on the show floor.

The International Microwave Symposium (IMS) took place in Denver in mid-June. It was also well attended and provided great opportunities to connect with potential new customers. This show will continue to grow in importance for us, given the focus on RF technology, which is one of our key markets. As IMS will be held in San Diego next year, it will create a great opportunity to showcase the new facility – we'll share more as we flesh out our plans for 2023.

Held in San Jose just a week after IMS, Sensors Converge was not quite as heavily attended as the prior events, but we did have an opportunity to engage with new and existing customers. MEMS and sensors are another key market for our business, and we look forward to participating in next year's event.

Going back to ECTC, our CEO Dick Otte chatted with 3D InCites' Francoise von Trapp during the show, as part of an ECTC podcast episode. Dick's segment, which begins at 28:05, touches on the CHIPS Act and its implications for the industry, as well as how data rates have exploded in the last decade along with evolution in the telecoms space. Please take a few minutes to listen, and let us know your thoughts!

We hope you're enjoying your summer, and we'll see you in September.





U.S. Chip Packaging with Mil-Spec Precision

A reliable and affordable alternative to ceramic packaging – Open-Cavity Plastic Packages (OCP).

Our latest white paper expands on the benefits of OCP for the mil-aero market. Download the paper here to learn how QP Technologies' OCP can save you time, space, and money.

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About Us

QP Technologies is a leading provider of microelectronic packaging and assembly, wafer preparation, and substrate design and development services. We leverage proven technologies developed by our skilled staff, and we work closely with you to get your products to market quickly, with the highest quality prototype and production volumes.



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